



Nanofluids Application in Heat Transfer

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Message from the Guest Editors

Dear Colleagues,

As guest editors, we are pleased to inform you about the Special Issue in the Journal of *Applied Sciences* with an Impact Factor of 2.474 by MDPI. The objective of this Special Issue (SI) is to encourage researchers, engineers, and scientists to present their latest innovative ideas, methods and results, and visions of the future related to the applications of various nanofluids in heat transfer problems, including (but not limited to) enhancement in various heat transfer modes, thermal management effectiveness in various heat exchange systems, thermal efficiency improvement in various energy conversion systems, thermal energy storage system, and so on. The existing literature indicates that studies on these topics are still limited. In order to fill this gap, researchers are invited to contribute their original research and review papers in these topics. Both experimental and numerical studies are welcomed.

Prof. Dr. Ching-Jenq Ho

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Guest Editors





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Message from the Editor-in-Chief

As the world of science becomes ever more specialized, researchers may lose themselves in the deep forest of the ever increasing number of subfields being created. This open access journal Applied Sciences has been started to link these subfields, so researchers can cut through the forest and see the surrounding, or quite distant fields and subfields to help develop his/her own research even further with the aid of this multi-dimensional network.

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